

APPLICATION
FOR
UNITED STATES LETTERS PATENT

TITLE: SEMICONDUCTOR DEVICE

APPLICANT: YOSHITAKA HARAGUCHI, NAOEI TAKEISHI AND
YOSHINORI HINO

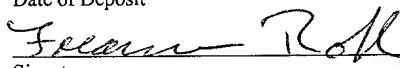
CERTIFICATE OF MAILING BY EXPRESS MAIL

Express Mail Label No. EF045065505US

I hereby certify under 37 CFR §1.10 that this correspondence is being deposited with the United States Postal Service as Express Mail Post Office to Addressee with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

February 21, 2002

Date of Deposit



Signature

Francisco Robles

Typed or Printed Name of Person Signing Certificate

SEMICONDUCTOR DEVICE

Background of the Invention

The present invention relates to a semiconductor device,
5 particularly a pattern layout construction of a display driver
and the like having an anode driver and a cathode driver for
example and making them in one chip.

A semiconductor device constituting the above-mentioned
display driver and the like will be described referring a
10 drawing.

In the above-mentioned display, there are various kinds
of flat panel displays such as an LCD, an LED display, an organic
EL (Electroluminescence) display, an inorganic EL display, a
PDP (Plasma Display Panel), an FED (Field Emission Display),
15 and so on.

An organic EL display driver will be described below as
an example, which has an anode driver and a cathode driver for
example, supplies constant current to the organic EL element,
and makes the organic EL element emit light. Since the EL element
20 has many merits such that a back light required in a liquid
crystal display is not necessitated because of
self-luminescence and that there is no limit about visual field
angle, application for display device of next generation is
expected. Especially, it is known that the organic EL element
25 is possible in high brightness and superior than an inorganic

EL element in high efficiency, high response characteristic, and multiple color.

The above-mentioned organic EL display driver includes logic N-channel MOS transistor and P-channel MOS transistor, 5 N-channel high-voltage MOS transistor and P-channel high-voltage MOS transistor of high withstand voltage, N-channel high-voltage MOS transistor and P-channel high-voltage MOS transistor of high withstand voltage reduced in on-resistance, N-channel MOS transistor for a level shifter, 10 and so on. Here, a DMOS (Double-diffused Metal-Oxide Semiconductor) transistor and the like are used for the high-voltage MOS transistor reduced in on-resistance for example. In the above-mentioned DMOS transistor construction, new diffusion region is formed by diffusing impurity different 15 in conductive type to diffusion region formed at surface side of semiconductor substrate and difference of vertical direction diffusion of these diffusion regions is used as effective channel length so that the transistor is an element suitable for low on-resistance by forming short channel.

20 A pattern layout of a semiconductor device at constituting various kinds of drivers such as the above-mentioned the organic EL display driver has constitution where required numbers of output of layouts for one bit output are arranged repeatedly.

25 Here, an anode driver, a cathode driver, a memory portion, and the like are constituted separately at constitution of the

above-mentioned organic EL display driver. Because of that, mounting them in one printing board is not satisfied in cost and size.

It is desired to design miniaturization of chip size and
5 low cost by making the anode driver, the cathode driver, the
memory portion, and the like in one chip.

Further, in the constitution only arranging various kinds
of drivers repeatedly times of necessary number of outputs,
space for drawing wiring around and the like is need so as to
10 bring enlargement of chip size.

That is, Fig. 17A is a plane view showing a pattern layout
of a semiconductor device constituting for driving display,
and layouts for output one bit are arranged repeatedly times
of necessary number of outputs as above-mentioned.

15 Here, numeral 1 in Fig. 17A denotes an output region
corresponding to one bit, and a driver portion having desired
number of outputs is constituted arranging plural output regions
1 for the one bit. Numeral 2 denotes wiring for a gate electrode
formed in the output regions 1, and source region (S) and drain
20 region (D) are formed to be adjacent to the wiring for the gate
electrode (See the enlarged figure in the circle of Fig. 17A).

The shape of the wiring 2 for gate electrode shown in Fig.
17A is only an example, and various kinds of wiring for gate
electrodes 2B, 2C, and 2D shown in Figs. 17B, 17C, and 17D may
25 be constituted. The above-mentioned constitution arranging

layout for output one bit repeatedly times of necessary number of outputs does not respond to a request for further multi bits at making in one chip because of the problem of inconvenience of drawing wiring around and taking space of drawing it around.

5 Furthermore, a problem of variation between bits rises as multi bits advance. That is, the variation between bits causes to generate micro-loading effect by difference between fineness and roughness of gate electrode forming pattern, and occasionally finishing shape and working dimension of the gate
10 electrode go wrong by the effect.

Especially, when the organic EL display driver having the anode driver, the cathode driver, and the like as above-mentioned are made in one chip, each driver portion is mounted mixedly naturally. Therefore, the above-mentioned difference between
15 fineness and roughness of the gate electrode forming pattern becomes large, micro-loading effect generates easily at photolithography and etching, variation of finishing shape and working dimension of the gate electrode caused by the effect becomes large, and being out of order in display generates.

20

Summary of the Invention

According to a first aspect of the present invention, in the semiconductor device of the present invention, desired drivers connected to the memory portions are laid out equally
25 in the chip and each memory portion is arranged equally in the

vicinity of each driver laid out equally in the semiconductor device made in one chip with an anode driver, a cathode driver, and memory portions.

5 Preferably, the desired drivers connected to the memory portions are divided into plural groups and each memory portion is arranged in every group.

Further, the desired drivers connected to the memory portions are placed face to face at right and left positions or high and low positions, and each memory portion is arranged 10 at center portion of the chip.

Moreover, the semiconductor constitutes each transistor for a driver and the each dummy pattern is formed to be adjacent to the end portion of the output bit group constituting a cathode driver, an anode driver, and an anode driver for icon.

15 Further, the dummy pattern is formed at an empty space in a region where the plural output bits are arranged.

Moreover, number of outputs of the dummy pattern formed at a region where output bit groups constituting the cathode driver, the anode driver, and the anode driver for icon are 20 adjacent each other is less than number of outputs of the dummy pattern formed at a region where output bit groups are not adjacent each other.

Further, the dummy pattern has the same shape as wiring for gate electrode.

25 According to the second aspect of the invention, in the

semiconductor device , plural output groups are arranged at periphery portion in the chip for drivers where plural output regions corresponding to one bit are arranged to constitute desired output bit group and made in one chip.

5 Preferably, wiring connected to each output bit arranged at the periphery portion is wired so as to circle fitting shape of the chip.

Further, the semiconductor device is applied to display drivers where drivers, memory portions, etc. are made in one 10 chip, and the drivers are arranged at periphery portion in the chip in the state of grouping by every desired output bit group, and wiring connected to each output bit arranged at the periphery portion is wired so as to circle fitting shape of the chip.

Moreover, the drivers are anode drivers and cathode drivers, 15 and the anode drivers or cathode drivers are arranged at periphery portion in the chip in the state of grouping by every desired output bit group, and that wiring connected to each output bit arranged at the periphery portion is wired so as to circle fitting shape of the chip.

20 Further, the wirings are a power source line and a signal line, and moreover, that the each output bit group is arranged so as to surround the memory portions at the periphery portion.

Moreover, the semiconductor constitutes each transistor for a driver and the each dummy pattern is formed to be adjacent 25 to the end portion of the output bit group constituting a cathode

driver, an anode driver, and an anode driver for icon.

Further, the dummy pattern is formed at an empty space in a region where the plural output bits are arranged.

Furthermore, number of outputs of the dummy pattern formed 5 at a region where output bit groups constituting the cathode driver, the anode driver, and the anode driver for icon are adjacent each other is less than number of outputs of the dummy pattern formed at a region where output bit groups are not adjacent each other.

10 Further, the dummy pattern has the same shape as wiring for gate electrode.

Brief Description of the Drawings

Figs. 1A and 1B are sectional views showing a method for 15 manufacturing a semiconductor device according to the embodiment of the invention;

Figs. 2A and 2B are sectional views showing a method for manufacturing a semiconductor device according to the embodiment of the invention;

20 Figs. 3A and 3B are sectional views showing a method for manufacturing a semiconductor device according to the embodiment of the invention;

Figs. 4A and 4B are sectional views showing a method for 25 manufacturing a semiconductor device according to the embodiment of the invention;

Figs. 5A and 5B are sectional views showing a method for manufacturing a semiconductor device according to the embodiment of the invention;

5 Figs. 6A and 6B are sectional views showing a method for manufacturing a semiconductor device according to the embodiment of the invention;

Figs. 7A and 7B are sectional views showing a method for manufacturing a semiconductor device according to the embodiment of the invention;

10 Figs. 8A and 8B are sectional views showing a method for manufacturing a semiconductor device according to the embodiment of the invention;

15 Figs. 9A and 9B are sectional views showing a method for manufacturing a semiconductor device according to the embodiment of the invention;

Figs. 10A and 10B are sectional views showing a method for manufacturing a semiconductor device according to the embodiment of the invention;

20 Figs. 11A and 11B are plane views showing a pattern layout of a semiconductor device according to the first embodiment of the invention;

Figs. 12 is a plane view showing a pattern layout of a semiconductor device according to the second embodiment of the invention;

25 Figs. 13 is a plane view showing a pattern layout of a

semiconductor device according to the second embodiment of the invention;

Figs. 14A to 14D are plane views showing a pattern layout of a semiconductor device according to the second embodiment 5 of the invention;

Figs. 15 is a plane view showing a pattern layout of a semiconductor device according to the third embodiment of the invention;

Fig. 16 is a plane view showing a pattern layout of the 10 conventional semiconductor device; and

Fig. 17 is a plane view showing a pattern layout of the conventional semiconductor device.

Detailed Description of the Preferred Embodiment

15 An embodiment of the invention according to a semiconductor device and a pattern layout method thereof will be described below with reference to the drawings. In this embodiment, an organic EL display is shown as an example, and a semiconductor device mounted with various kinds of MOS 20 transistors constituting the organic EL display driver is described.

The organic EL display driver is configured with, as viewed from the left in Fig. 10A, logic N-channel MOS and P-channel MOS transistors (e.g. on 3 V), an N-channel MOS transistor (e.g. 25 on 30 V) for a level shifter and an N-channel high-voltage MOS

transistor of high withstand voltage (e.g. on 30 V) and, as viewed from the left in Fig. 10B, an N-channel high-voltage MOS transistor of high withstand voltage (e.g. on 30 V) reduced in on-resistance, a P-channel high-voltage MOS transistor of 5 high withstand voltage (e.g. on 30 V) and a P-channel high-voltage MOS transistor of high withstand voltage (e.g. on 30 V) reduced in on-resistance. Note that, in the below explanation, the MOS high-voltage transistor reduced in on-resistance is referred to as an SLED (Slit channel by counter doping with 10 extended shallow drain) MOS transistor in order to differentiate between the high-voltage MOS transistor and the high-voltage MOS transistor reduced in on-resistance, for the sake of explanation.

In the semiconductor device mounted with various MOS 15 transistors constituting such an organic EL display driver, as shown in Figs. 10A and 10B, an N type well region 23 forming the P-channel high-voltage transistor and the P-channel high-voltage SLEDMOS transistor reduced in on-resistance is configured in a step higher region, while a P type well region 20 22 forming the other MOS transistors is configured in a step lower region. In other words, structuring is made to arrange the precise logic (e.g. 3V) N-channel MOS and P-channel MOS transistors in the step lower region.

Explanation is made below on a method of manufacturing 25 a semiconductor device mounted with various transistors

constituting the display driver described above.

In Figs. 1A and 1B, in order to define a region for forming various MOS transistors, a P type well (PW) 22 and an N type well (NW) 23 are first formed using LOCOS technique, e.g. in 5 a p type semiconductor substrate (P-sub).

That is, although explanation with showing is omitted, a pad oxide film and a silicon nitride film are formed on the well region of the semiconductor substrate 21. The pad oxide film and silicon nitride film is used as a mask to ion-implant 10 boron ion, for example, at an acceleration voltage of approximately 80 keV and a dose of $8 \times 10^{12} / \text{cm}^2$, thereby forming an ion-implant region. Thereafter, the silicon nitride film is used as a mask to oxidize the substrate surface by the LOCOS 15 technique, thereby forming a LOCOS film. At this time, the boron ion implanted in a region beneath the LOCOS film is diffused toward the inward of the substrate to form a P type region .

Next, the pad oxide film and the silicon nitride film are removed. Thereafter, the LOCOS film is used as a mask to ion-implant phosphorus ion to the substrate surface, at an 20 acceleration voltage of approximately 80 keV and a dose of $9 \times 10^{12} / \text{cm}^2$, thereby forming an ion-implant region 15. Then, the LOCOS film is removed away. Thereafter, the impurity ions implanted in the substrate are thermally diffused to form a P type well and N type well. Thus, as shown in Figs. 1A and 25 1B, the P type well 22 formed in the substrate 21 is arranged

in a step lower region while the N type well is arranged in a step higher region.

Next, in Figs. 2A and 2B, a device isolation film 24 is formed to an approximately 500 nm by the LOCOS process in order 5 for device isolation based on the MOS transistor. A thick gate oxide film 25 for withstanding high voltage is formed by thermal oxidation in a thickness of approximately 80 nm on an active region excepting the device isolation region.

Subsequently, the resist film is used as a mask to form 10 first low-concentration N type and P type source/drain regions (hereinafter, referred to as LN region 26, LP region 27). Namely, in a state covering the region of other than an LN region by a not-shown resist film, phosphorus ion, for example, is first ion-implanted to the substrate surface layer at an acceleration 15 voltage of 120 keV and a dose of $8 \times 10^{12} / \text{cm}^2$ thereby forming an LN region 26. Thereafter, in a state covering the region of other than an LP region by a resist film (PR), boron ion, for example, is ion-implanted to the substrate surface layer at an acceleration voltage of 120 keV and a dose of $8.5 \times 10^{12} / \text{cm}^2$ thereby forming an LP region 27. Note that, in actual, 20 the implanted ionic species will be thermally diffused into a LN region 26 and LP region 27 through an anneal process as a later process (e.g. in an N_2 atmosphere at 1100°C for 2 hours).

Subsequently, in Figs 3A and 3B, using as a mask a resist 25 film at between the LN regions 26 and the LP regions 27 forming

the regions for P-channel and N-channel SLEDMOS transistors, second low-concentration N type and P type source/drain regions (hereinafter, referred to as SLN region 28 and SLP region 29) are formed. Namely, in a state covering the region other than 5 the region for an SLN region by a not-shown resist mask, phosphorus ion, for example, is first ion-implanted to the substrate surface layer at an acceleration voltage of 120 keV and a dose of $1.5 \times 10^{12} / \text{cm}^2$ to form an SLN region 28 continuing the LN regions 26. Then, in a state covering the other region 10 of the SLP region by a resist film (PR), boron difluoride ($^{49}\text{BF}_2^+$), for example, is ion-implanted to the substrate surface region at an acceleration voltage of 140 keV and a dose of $2.5 \times 10^{12} / \text{cm}^2$ to form an SLP region 29 continuing the LP regions 27. Note that the LN region 26 and the SLN region 28 or the LP region 15 27 and the SLP region 29 are set nearly equal in impurity concentration or higher in either one.

Furthermore, in Figs. 4A and 4B, a resist film is used as a mask to form high-concentration N type and P type source/drain regions (hereinafter, referred to as N+ region 20 30, P+ region 31). Namely, in a state covering the other region than a region for an N+ region by a not-shown resist film, phosphorus ion, for example, is first ion-implanted to the substrate surface layer at an acceleration voltage of 80 keV and a dose of $2 \times 10^{15} / \text{cm}^2$ thereby forming an N+ region 30. 25 Thereafter, in a state covering the other region than a region

for a P+ region by a resist film (PR), boron difluoride ion, for example, is ion-implanted to the substrate surface layer at an acceleration voltage of 140 keV and a dose of 2×10^{15} /cm² thereby forming a P+ region 31.

5 Next, in Figs. 5A and 5B, using as a mask a resist film having an opening diameter smaller than the mask opening diameter (see Fig. 3) for forming the SLN region 28 and SLP region 29, opposite-conductivity type impurities are ion-implanted to a central area of the SLN region 28 continuing the LN regions 10 26 and to a central area of the SLP region 29 continuing the LP regions 27, thereby forming a P type body region 32 and an N type body region 33 to respectively separate the SLN region 28 and the SLP region 29. Namely, in a state covering the other region than the region for a P type region by a not-shown resist 15 film, boron difluoride ion, for example, is first ion-implanted to the substrate surface layer at an acceleration voltage of 120 keV and a dose of 5×10^{12} /cm² thereby forming a P type body region 32. Thereafter, in a state covering the other region than the region for an N type region by a resist film (PR), 20 phosphorus ion, for example, is ion-implanted to the substrate surface layer at an acceleration voltage of 190 keV and a dose of 5×10^{12} /cm² thereby forming an N type body region 33. Note that the operation processes concerning ion implant shown in Figs. 3A to 5B may be properly changed in order. The P type 25 body region 32 and the N type body region 33 each will be

constituted with a channel in a surface region thereof.

Furthermore, in Figs. 6A and 6B, a second P type well (SPW) 34 and a second N type well (SNW) 35 are formed in the substrate (P type well 22) at a region for precise N-channel 5 and P-channel MOS normal-voltage transistors.

Namely, using a not-shown resist film having an opening in the region for an N-channel normal-voltage MOS transistor as a mask, boron ion, for example, is ion-implanted to the P type well 22 at an acceleration voltage of approximately 190 10 keV and a dose of (first implant condition) $1.5 \times 10^{13} / \text{cm}^2$. Thereafter, boron ion is again ion-implanted at an acceleration voltage of approximately 50 keV and a dose of (second implant condition) $2.6 \times 10^{12} / \text{cm}^2$, thus forming a second P type well 34. Also, using a resist film (PR) having an opening in the 15 region for a P-channel normal-voltage MOS transistor as a mask, phosphorous ion, for example, is ion-implanted to the P type well 22 at an acceleration voltage of approximately 380 keV and a dose of $1.5 \times 10^{13} / \text{cm}^2$, thereby forming a second N type well 35. Note that, where a high-acceleration voltage 20 generating apparatus having nearly 380 keV is not available, it is satisfactory to use a double charge scheme for ion-implant two-valence phosphorus ion at an acceleration voltage of approximately 190 keV and a dose of $1.5 \times 10^{13} / \text{cm}^2$. Subsequently, phosphorus ion is ion-implanted at an acceleration voltage of 25 approximately 140 keV and a dose of $4.0 \times 10^{12} / \text{cm}^2$.

Next, removed is the oxide film 25 from the regions for N-channel and P-channel normal-voltage MOS transistors and for a level-shifter N-channel MOS transistor. Thereafter, as shown in Figs. 7A and 7B, a gate oxide film having a desired film thickness is newly formed on the above region.

Namely, a gate oxide film 36 is formed on the entire surface by thermal oxidation to approximately 14 nm (approximately 7 nm at this stage, but the film thickness will increase upon forming a gate oxide film for normal voltage referred later) for a level-shifter N-channel MOS transistor. Subsequently, after removing the gate oxide film 36 for a level-shifter N-channel MOS transistor formed on the region for N-channel and P-channel normal-voltage MOS transistors, a thin gate oxide film 37 (approximately 7 nm) for normal voltage is formed on this region by thermal oxidation.

Subsequently, in Figs. 8A and 8B, a polysilicon film having approximately 100 nm is formed over the entire surface. The polysilicon film is thermally diffused by POCl_3 as a thermal-diffusion source thus being made conductive. Thereafter, a tungsten silicide film having approximately 100 nm are formed on the polysilicon film, and further an SiO_2 film having approximately 150 nm thereon. Using a not-shown resist film, patterning is made to form gate electrodes 38A, 38B, 38C, 38D, 38E, 38F, 38G for MOS transistors. Note that the SiO_2 film serves as a hard mask during the patterning.

Subsequently, in Figs. 9A and 9B, low-concentration source/drain regions are formed for normal-voltage N-channel and P-channel MOS transistors.

Namely, using as a mask a not-shown resist film covering 5 the other region than the region for low-concentration source/drain regions for a normal-voltage N-channel MOS transistor, phosphorus ion, for example, is ion-implanted at an acceleration voltage of approximately 20 keV and a dose of 10 $6.2 \times 10^{13} / \text{cm}^2$ to form low-concentration N- type source/drain regions 39. Meanwhile, using as a mask a resist film (PR) covering the other region than the region for a low-concentration source/drain region for a normal-voltage P-channel MOS transistor, boron difluoride ion, for example, is ion-implanted 15 at an acceleration voltage of approximately 20 keV and a dose of $2 \times 10^{13} / \text{cm}^2$ to form low-concentration P- type source/drain regions 40.

Furthermore, as shown in Figs. 10A and 10B, a TEOS film 41 having approximately 250 nm is formed over the entire surface by the LPCVD process in a manner covering the gate electrodes 20 38A, 38B, 38C, 38D, 38E, 38F, 38G. The TEOS film 41 is anisotropically etched through a mask of a resist film (PR) having openings in the region for normal-voltage N-channel and P-channel MOS transistors. This forms sidewall spacer films 41A on the sidewalls of the gate electrode 38A, 38B, as shown 25 in Fig. 10A. The TEOS film 41 is left, as it is, in the region

covered by the resist film (PR).

Then, using the gate electrode 38A, sidewall spacer films 41A, gate electrode 38B and sidewall spacer films 41A as a mask, high-concentration source/drain regions are formed for 5 normal-voltage N-channel and P-channel MOS transistors.

Namely, using a not-shown resist film covering the other region than the region of high-concentration source/drain regions for a normal-voltage N-channel MOS transistor as a mask, arsenic ion, for example, is ion-implanted at an acceleration 10 voltage of approximately 100 keV and a dose of $5 \times 10^{15} / \text{cm}^2$ thereby forming high-concentration N+ source/drain regions 42. Also, using a not-shown resist film covering the other region than the region of high-concentration source/drain regions for a normal-voltage P-channel MOS transistor as a mask, boron 15 difluoride ion, for example, is ion-implanted at an acceleration voltage of approximately 40 keV and a dose of $2 \times 10^{15} / \text{cm}^2$ thereby forming high-concentration P+ source/drain regions 43.

An interlayer insulating film, including TEOS and BPSG films, is formed to approximately 600 nm and, thereafter, a 20 metal interconnection layer is formed to have contact to the source/drain regions 30, 31, 42, 43. Thus, completed are normal-voltage N-channel and P-channel MOS transistors, a level-shifter N-channel MOS transistor, high-voltage N-channel and P-channel MOS transistors, and high-voltage N-channel and 25 P-channel SLEDMOS transistors reduced in on-resistance, to

constitute the organic EL display driver.

Here, the invention discloses an efficient pattern layout method at making an anode driver, a cathode driver, a memory portion memorizing display data etc., a controller, and the like in one chip in an organic EL display driver which supplies constant current to an organic EL element (organic electroluminescent element), and makes the organic EL element emit light.

(Embodiment 1)

10 Outline about pattern layout constitution of the first embodiment will be described below with reference to drawings.

In Fig. 11A, making the anode driver, the cathode driver, the memory, the controller, and the like in one chip, the following regions are arranged: from upper left of the paper, 15 anode driver region 110 of 32 bits (segment: SEG); cathode driver region 111 of 128 bits (common: COM); and anode driver region 112 of 32 bits (SEG); and from lower left of the paper, anode driver region 113 of 32 bits (SEG); anode driver region 114 for icon of 10 bits (icon SEG); anode driver region 115 for 20 icon of 10 bits (icon SEG); and anode driver region 116 of 32 bits (SEG). Each of driver regions constitutes desired output bit group by arranging repeatedly output region corresponding to one bit output at times of numbers of required outputs.

25 SRAMs (Static Random Access Memory) 118 and 119 as memory

portions are arranged at symmetric positions through another logic portion 117 in the center portion, and output wiring 120 from the SRAMs 118 and 119 is connected to each of the anode driver regions 110, 112, 113, and 116. These may be symmetric 5 positions of high and low putting depending on the arrangement in the chip though symmetry of right and left in this embodiment.

Thus in the invention, drawing the wiring 120 around becomes easy by arranging the anode drivers connected to the SRAMs at four corners in the chip, dividing the SRAMs into two 10 parts putting together with each of anode drivers 110, 112, 113, and 116, and corresponding a group of the anode driver regions 110 and 113 arranged at left end portion of the chip to a group of the anode driver regions 112 and 116 arranged at right end portion of the chip respectively.

15 That is, to describe with comparison of the conventional constitution (Fig. 16) and the above-mentioned constitution of Fig. 11A, when output pads 3 corresponding to all drivers are arranged in one line in the chip as shown in Fig. 16, space of drawing wiring 5 around (region encircled with a circle in 20 Fig. 16) is required so that chip size increases for the space because the wiring 5 is drawn around to each output pad 3 from the memory portion 4 arranged at one position.

On the contrary, in the invention, space of drawing around is small because of arranging the drivers (anode driver in this 25 embodiment) connected to the SRAMs at four corners in the chip,

dividing the SRAMs into two parts putting together with each of anode drivers 110, 112, 113, and 116, and wiring each of the anode driver regions 110, 112, 113, and 116 to the SRAMs 118 and 119.

5 Further, to describe with comparison of the constitution shown in Fig. 11B and the above-mentioned constitution of Fig. 11A, in the constitution shown in Fig. 11B, the driver (anode driver in this embodiment) connected to the SRAMs similarly as the constitution of Fig. 11A. However, space of drawing 10 the wiring 120 around becomes large as compared with the constitution of the above-mentioned Fig. 11A, but small as compared with constitution of the above-mentioned Fig. 16 because the SRAMs (118 and 119) connected to each of anode driver regions 110, 112, 113, and 116 are arranged at one position.

15 Moreover, since constitution of Fig. 11A is symmetry of right and left in length of wiring, influence caused by impedance is reduced as compared with constitution of Fig. 16 so that uneven of display can be depressed.

As described above, when the organic EL display driver 20 having the anode driver, the cathode driver, the memory portion and the controller is made in one chip, miniaturization of the chip size is designed and low cost becomes possible by dividing the memory portion into two parts because wiring length of drawing around at connecting the memory portion and each driver.

25 Although the anode driver regions 110, 112, 113, and 116

connected to the memory portions are arranged equally at four corners of the chip so as to divide the anode driver regions 110, 112, 113, and 116 into two groups, and the memory portions are divided into two parts (SRAMs 118 and 119) so as to correspond 5 to each group in the mode for carrying out, the memory portions may be subdivided.

(Embodiment 2)

The pattern layout constitution of the second embodiment of the invention will be described referring the drawings. The 10 description of similar constitution as the background art (Figs. 17A to 17D) is omitted adding the same symbols to avoid repeated description.

In Fig. 12, numeral 1 denotes output region corresponding to output one bit, and layout of a semiconductor device 15 constituting various kinds of drivers such as a driver for driving an organic EL display and the like constitutes desired output group by arranging the output region 1 for one bit repeatedly times of necessary outputs.

In the output region 1 for one bit, wiring for gate electrode 20 is formed similarly as Figs. 17A to 17D.

In this embodiment, the following regions are arranged: from upper left of the paper, anode driver region 210 of 32 bits (segment: SEG); cathode driver region 211 of 128 bits (common: COM); and anode driver region 212 of 32 bits (SEG); 25 and from lower left of the paper, anode driver region 213 of

32 bits (SEG); anode driver region 214 for icon of 10 bits (icon SEG); anode driver region 215 for icon of 10 bits (icon SEG); and anode driver region 216 of 32 bits (SEG) making the anode driver, the cathode driver, the memory, the controller, and
5 the like in one chip. Each of driver regions constitutes desired output bit group by arranging repeatedly output region 1 corresponding to one bit output times of numbers of required outputs.

Thus in the invention, each of driver regions (an anode driver region 210, a cathode driver region 211, an anode driver region 212, an anode driver region 213, an anode driver region 214 for icon, an anode driver region 215 for icon, and an anode driver region 216) is arranged equally at periphery portion in the chip, and at almost center portion of the chip, memory portions 217 and 218 memorizing display data etc., controller, and the like are arranged. Wiring 219 of power source line, signal line, and the like are drawn around each driver region, and the wiring 219 is connected at every output region for one bit.

20 As described above, at making the anode driver, the cathode driver, the memory portion, the controller and the like in one chip, driver outputs can be arranged to all of four directions, for example, by drawing wiring 219 of the power source line, the signal line, and the like around fitting the to shape of
25 the chip.

By arranging the memory portion, the controller, and the like at the center portion of the chip, efficiency of wiring becomes good so as to design miniaturization of chip size. That is, memory portions 217 and 218 including SRAMs are arranged 5 at symmetric positions of the center portion of the chip as shown in Fig. 13, and output wiring 220 from the memory portions 217 and 218 is connected to each of the anode driver regions 210, 212, 213, and 216. These may be symmetric positions of 10 high and low putting depending on arrangement in the chip though symmetry of right and left in this embodiment.

Thus in the invention, drawing the wiring 220 around becomes easy by arranging the drivers (the anode drivers in this embodiment) connected to the memory portions 217 and 218 to four directions of the periphery portion in the chip, dividing 15 the memory portions into two parts putting depending on each of anode drivers 210, 212, 213, and 216, and corresponding a group of the anode driver regions 210 and 213 arranged at left end portion of the chip to a group of the anode driver regions 212 and 216 arranged at right end portion of the chip respectively. 20 By reduction of the space of drawing around, miniaturization of chip size is designed for the reduction.

Another layout method of each driver region arranged in the chip will be described referring Figs. 14A to 14D. Fig. 14A shows the pattern layout shown in Fig. 13 typically, and 25 the variations of arrangement of Fig. 14A are arrangement of

Figs. 14B, 14C, and 14D described below. Memory portions are omitted for convenience.

First, in the arrangement example shown in Fig. 14B, anode driver regions 213 and 216 placed face to face respectively 5 at upper and lower position against the driver regions 210 and 212 with respect to the paper face are arranged to be adjacent respectively to the anode driver regions 210 and 212 in 90 degrees, and anode driver regions 214 and 215 for icon are arranged to be adjacent respectively to the driver regions 213 and 216. 10 Thus, comparatively wide region of lower side of the chip against becomes vacant so that degree of freedom at arrangement of another logic portion, controller, and the like increases.

Further, in the arrangement example shown in Fig. 14C, anode driver regions 214 and 215 for icon and anode driver regions 15 213 and 216 are arranged in the vicinity respectively in Fig. 14A, and anode driver regions 210 and 212 are arranged so as to be adjacent 90 degrees respectively to the anode driver regions 213 and 216. Thus, chip size can be miniaturized as compared with arrangements of Figs. 14A and 14B.

20 Moreover, in the arrangement example shown in Fig. 14D, chip size is similar as chip sizes shown in Figs. 14A and 14B so that further multi bits are designed but the arrangement example shown in Fig. 14C is better in miniaturization than the arrangement example shown in Fig. 14D. Numerals 208, 209, 25 and 211A denotes an anode driver region and a cathode driver

region made in more multi bits than the anode driver region and the cathode driver region in the above-mentioned Figs. 14A, 14B, and 14C respectively.

(Embodiment 3)

5 The pattern layout constitution of the third embodiment of the invention will be described referring the drawings. The description of similar constitution as the background art (Figs. 17A to 17D) is omitted adding the same symbols to avoid repeated description.

10 The third embodiment has a feature in the semiconductor device and pattern layout method thereof with the object of designing improvement of precision of finishing shape and working dimension of the each of gate electrode.

15 Fig. 15 is a view showing pattern layout of the third embodiment applied to an organic EL display driver.

In Fig. 15, numeral 1 denotes output region corresponding to one bit, and pattern layout of a semiconductor device for various kinds of drivers such as a display driver and the like constitutes desired output bit group by arranging repeatedly 20 the output regions 1 for one bit with times of numbers of required output are arranged to have desired numbers of output.

Similar to the conventional output region, wiring for gate electrode is formed in the output region 1 for one bit, and source region and drain region are formed to be adjacent to 25 the wiring for gate electrode.

Symbol 303A to 303N is dummy patterns which is a feature of this embodiment, and the dummy patterns 303A to 303N are formed to be adjacent to an end portion of the output bit group where the output region 1 for one bit is arranged repeatedly.

5 In the dummy patterns 303A to 303N, wiring for the dummy gate electrode having the same shape as the wiring for gate electrode formed in the output region 1 for one bit is formed. Here, source region and drain region corresponding to the wiring for the dummy gate electrode of are not constituted.

10 Here, as the above-mentioned display driver for driving display, there is an organic EL display driver and the like having an anode driver and a cathode driver for example, supplying constant current to an organic EL element (an organic electroluminescent element), and makes the organic EL element emit light. When the driver for driving organic EL display driver having the anode driver, the cathode driver, a memory, a controller, and the like are made in one chip, each driver portion is mounted mixedly naturally. Therefore, the above-mentioned difference between fineness and roughness of 15 the gate electrode forming pattern becomes large, micro-loading effect generates easily at photolithography and etching, dispersion variation of finishing shape and working dimension of the gate electrode caused by the effect becomes large, and problem being out of order in display generates.

20

25 Then, in the invention, making the anode driver, the

cathode driver, the memory, the controller, and the like in one chip, the following regions are arranged: from upper left of the paper, anode driver region 310 of 32 bits (segment: SEG); cathode driver region 311 of 128 bits (common: COM); and anode 5 driver region 312 of 32 bits (SEG); and from lower left of the paper, anode driver region 313 of 32 bits (SEG); anode driver region 314 for icon of 10 bits (icon SEG); anode driver region 315 for icon of 10 bits (icon SEG); and anode driver region 316 of 32 bits (SEG). Each of driver regions constitutes desired 10 output bit group by arranging repeatedly output region 1 corresponding to one bit output at times of numbers of required outputs.

At one end portion (the end side of the pattern) of the anode driver region 310 of 32 bits (SEG), SEG dummy pattern 15 303A for 2 bits (two pieces of the output region 1) is arranged, and at another end portion (center side of the pattern), SEG dummy pattern 303B for one bit is arranged. At one end portion (the SEG dummy pattern 303B side) of the cathode driver region 311 of 128 bits (COM), COM dummy pattern 303C for one bit is 20 arranged to be adjacent to the SEG dummy pattern 303B, and even at another end portion, COM dummy pattern 303D for one bit is arranged. Further, at one end portion (the SEG dummy pattern 303D side) of the anode driver region 312 of 32 bits (SEG), SEG dummy pattern 303E for one bit is arranged to be adjacent 25 to the COM dummy pattern 303D, and at another end portion (end

side of the pattern), SEG dummy pattern 303F for 2 bits is arranged.

At one end portion (the end side of the pattern) of the anode driver region 313 of 32 bits (SEG), SEG dummy pattern 5 303G for 2 bits is arranged, and at another end portion (center side of the pattern), SEG dummy pattern 303H for one bit is arranged. At one end portion (the SEG dummy pattern 303H side) of the cathode driver region 314 of 10 bits (icon SEG), icon SEG dummy pattern 303I for one bit is arranged to be adjacent 10 to the SEG dummy pattern 303H, and even at another end portion, icon SEG dummy pattern 303J for 2 bits is arranged. Further, at one end portion (the center side of the pattern) of the anode driver region 315 for icon of 32 bits (icon SEG), icon SEG dummy pattern 303K for 2 bits is arranged, and at another end portion 15 (the anode driver region 316 of 32 bits (SEG) side), icon SEG dummy pattern 303L for one bit is arranged. At one end portion (the SEG dummy pattern 303L side) of the anode driver region 316 of 32 bits (SEG), SEG dummy pattern 303M for one bit is arranged, and at another end portion (the end side of the pattern), 20 SEG dummy pattern 303N for 2 bits is arranged.

Numerals 317 and 318 denote memories arranged at a pattern center portion and memorizing display data and the like.

At this time, working precision is improved by forming a dummy pattern of the same shape as each output bit at the 25 end portion at every each output bit group in this embodiment.

Further, by applying the invention for display driver and the like having an anode driver, a cathode driver, and so on, variation of working precision can be depressed even at making them in one chip. Therefore, michronization and low cost are 5 designed comparing the conventional driver having them separately by making in one chip.

Furthermore, each dummy pattern does not formed evenly (i.e. the same output number), but number of output (one bit in this embodiment) of dummy pattern arranged at the region 10 where adjacent output bit group exists is made less than number of output (2 bits in this embodiment) of the dummy pattern arranged at the region where adjacent output bit group does not exist.

Thus, when output bit group adjacent to end portion of 15 output bit group does not exist, dummy pattern for 2 bits is arranged for example in the invention. When the output bit group adjacent exists, effectual use of pattern is designed without vain increasing of pattern area by arranging dummy pattern for one bit for example at every output bit group adjacent 20 (i.e. joining each dummy pattern formed at every output bit pattern adjacent becomes a pattern for 2 bits). Even in the case that output bit group adjacent exists, dummy pattern of the same number (pattern for 2 bits for example) as in the case that output bit group adjacent does not exist at end portion 25 of the output bit group may be arranged.

Further, if there is an empty space not patterned in region where plural output bit regions are arranged, not only forming the dummy pattern at the end portion of the output bit group, a dummy pattern may be formed in the empty space. Thus in the 5 invention, the dummy pattern may be arranged at desired position with desired rate considering relation of fineness and roughness of working pattern.

Although a driver for driving the organic EL display for display is described as an example in the above embodiments, 10 the invention is not limited to this. The invention is applicable to drivers for various kinds of flat panel display such as an LCD, an LED display, an inorganic EL display, a PDP (Plasma Display Panel), an FED (Field Emission Display), and so on for example, and is possible to apply for use that circuits 15 are inserted repeatedly and number of bits is determined as the need arises. Further, provision of the dummy pattern described in the third embodiment is applicable to the semiconductor device of the first and second embodiments.

According to the invention, at first, at making the driver 20 for driving display having the anode driver, the cathode driver, the memory, and the like in one chip, the driver regions connected to the memory portions are laid out equally in the chip, and the memory portions are arranged in divided parts corresponding to each region laid out equally. Because of that, drawing of 25 wiring between the memory portions and the drivers becomes easy,

and miniaturization of the chip size can be designed because length of wiring at the memory portions becomes short.

Second, space of drawing wiring around is miniaturized by arranging driver regions equally at periphery portion in 5 the chip, drawing wiring such as power source line, signal line, and the like around each driver region. By arranging the memory portion etc. at center portion of the chip, efficiency of wiring become good so as to design miniaturization of chip size.

Further, by applying the invention for a driver for driving 10 display having an anode driver, a cathode driver, and the like, these can be made in one chip so as to design miniaturization and low cost.

Third, working precision can be improved by forming the 15 dummy pattern at the end portion of the output bit group.

By applying to the display driver having the anode driver, the cathode driver, and the like, it is possible to make them in one chip so that miniaturization and low cost are designed. Further, there is not vain increasing of pattern area by arranging number of output of the dummy pattern arranged at 20 region where output bit group adjacent exists less than number of output of the dummy pattern arranged at region where the output bit group adjacent does not exist.